

## USE OF ENGINEERING TOOLS CASE HISTORIES

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Handout 1b.2



## **COMPANY PROFILE**

- SMALL BUSINESS
- ESTABLISHED IN 1987
- ARIZONA CORPORATION
- EMPLOYEE OWNED WITH 35 EMPL.
- PRINTED CIRCUIT BOARD MANUF.
- MILITARY AND COMMERCIAL
- SHORT INTERVAL MANUFACTURER





# **CAPABILITY PROFILE**

- DOUBLE SIDED THROUGH 20 LAYERS
- EPOXY, POLYIMIDE, TEFLON, KAPTON
- RIGID, FLEX, AND RIGID FLEX
- CONTROLLED IMPEDANCE
- BLIND AND BURIED VIAS



- 7 MIL PITCH AND 5 MIL LINES/SPACES
- HIGH ASPECT RATIO





# **CAPABILITY PROFILE**

- SURFACE FINISHES
  - SOLDER COAT AND FUSED TIN LEAD
  - GOLD, NICKEL, TIN NICKEL
  - IMMERSION TIN
- ELECTRICAL TESTING
  - SIMULTANEOUS TOP AND BOTTOM
  - FIXTURED NET LIST AT 80 MIL GRID
  - FIXTURELESS FLYING PROBE







## EXPERTISE

- MFG. COMPLEX PRODUCTS
- ENGINEERING SOLUTIONS



- DELIVERY IN SHORT INTERVAL
- DESIGN FOR MANUFACTURE
- PROCESS CONSISTENCY
- FOCUS ON CUSTOMER SATISFACTION



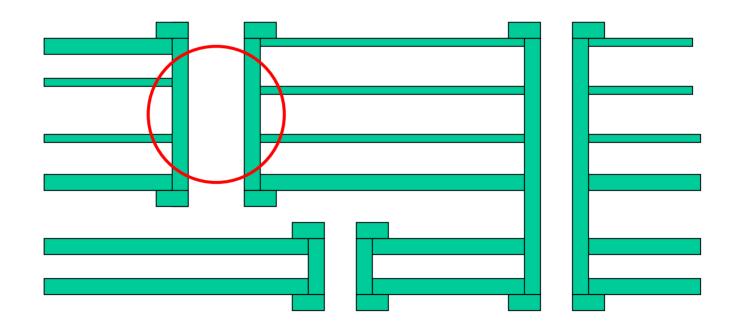
# USE OF ENGINEERING TOOLS CASE 1

- SIX LAYER DOUBLE BLIND VIA
- PROBLEM OF FATIGUE FAILURE IN VIA
- CUSTOMER W/O ANALYTICAL TOOLS
- SEARCHED THE WEB FOR SOLUTIONS
- LOCATED "U-ENGINEER" AT GA TECH
- SOLICITED HELP FROM GA -TECH
- FINITE ELEMENT ANALYSIS



### **CASE 1 LAY-UP**

### • LAYER 1-4 BLIND & 5-6 BLIND





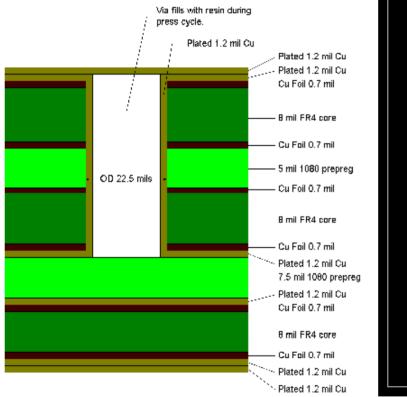
# USE OF ENGINEERING TOOLS CASE 1 CONTINUED

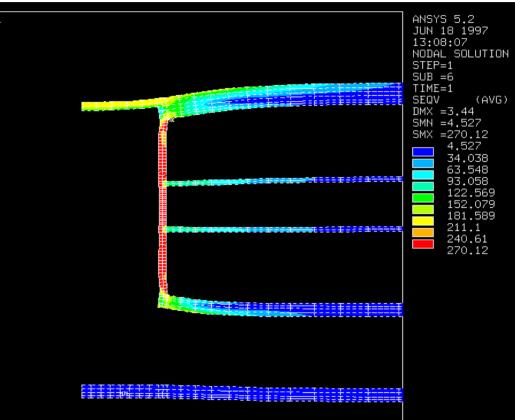
- ANALYSIS OF PLATED THROUGH HOLES
- PREDICTED FATIGUE FAILURE OF BLIND VIA DURING 2ND PRESS CYCLE
- BOARD REDESIGNED TO REDUCE BARREL STRESSES



# **Case 1 Analysis Results**

#### Plated Through Via





Barrel Stress > Ultimate Strength (~260MPa), so predicts original design will fail. *Conclusion:* Analysis before mfg. would have prevented scrap & delays.



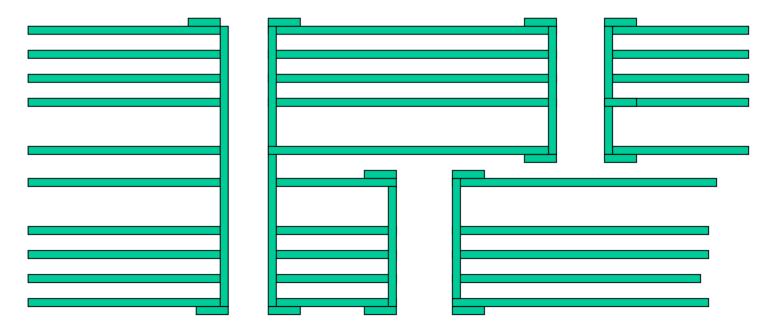
### USE OF ENGINEERING TOOLS CASE STUDY 2

- TEN LAYER DOUBLE BLIND VIA
- EPOXY, FIVE CORE, 80 MILS THICK
- COST SENSITIVE
- RELIABILITY ISSUES AFTER
  THERMAL CYCLE
- FATIGUE ANALYSIS PREDICTED
  RELIABILITY WITH POLYIMIDE



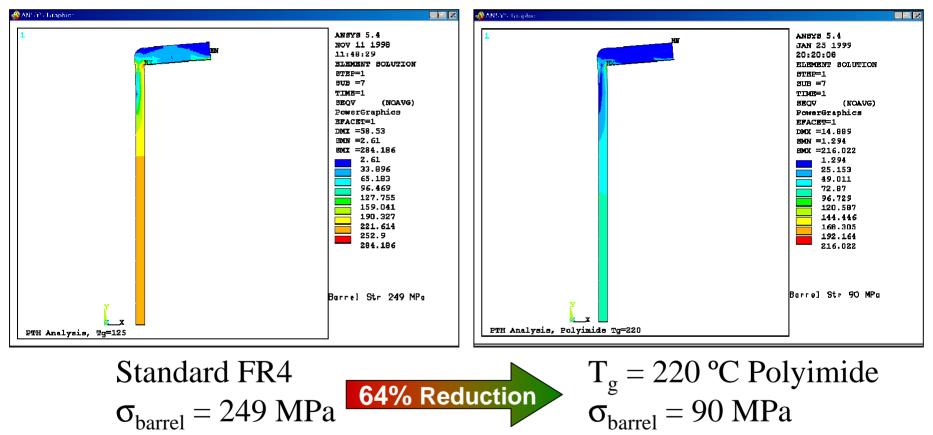
### **CASE 2 LAY- UP**

### • LAYERS 1-5 & 6-10 ARE BLIND





### **Case 2 Analysis Results**



*Conclusion:* Polyimide design chosen to reduce stress and increase reliability

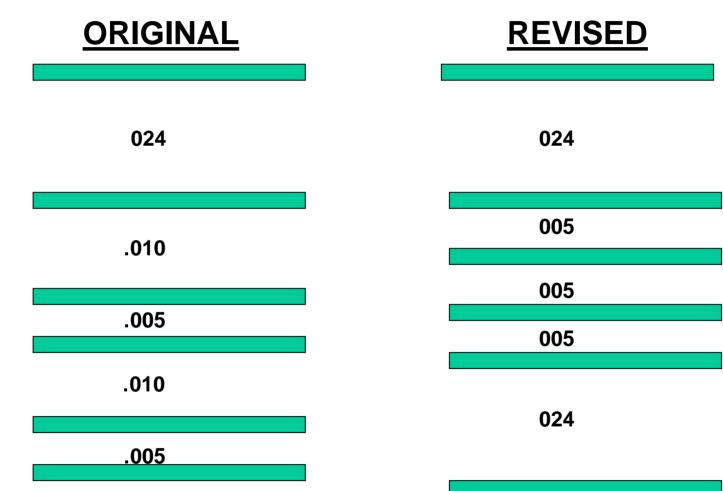


# USE OF ENGINEERING TOOLS CASE STUDY 3

- SIX LAYER, 67 MILS THICK WITH NON-SYMMETRICAL Z AXIS
- SEVERE WARP
- WARP ANALYSIS PREDICTED
  THERMAL DISTORTION
- MODELED CONSTRUCTION
  VARIABLES REDUCED
  DISTORTION



### **CASE 3 LAY- UP**



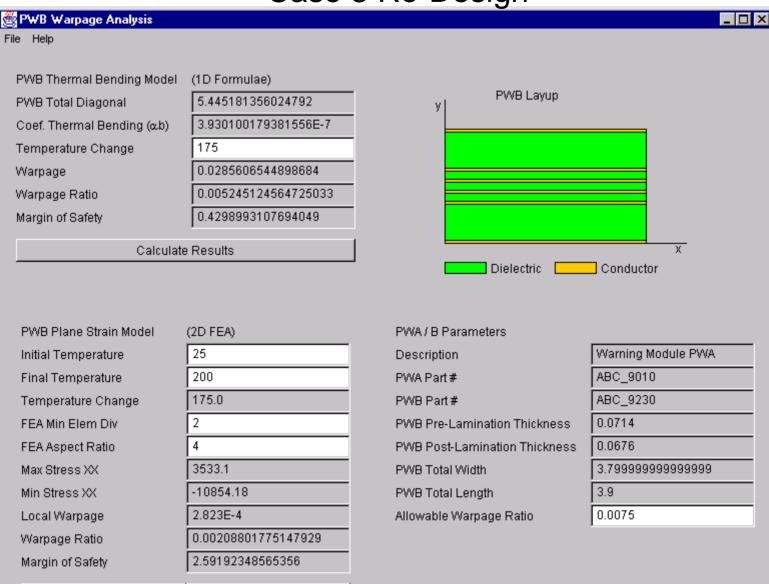
### Case 3 Original

DV/D V/ A			
PWB Warpage Analysis e Help			
e nep			
PWB Thermal Bending Model	(1D Formulae)		
PWB Total Diagonal	5.445181356024792	PWB Layup	
Coef. Thermal Bending (α.b)	0.005570211573007959		
Temperature Change	175		
Warpage	463.1800528757218		
Warpage Ratio	85.06237397644043		
Margin of Safety	-0.9999118294064767		
Colculat	e Results		X
		Dielectric	Conductor
PWB Plane Strain Model	(2D FEA)	PWA / B Parameters	
Initial Temperature	25	Description	Warning Module PWA
Final Temperature	200	PWA Part#	ABC_9010
Temperature Change	175.0	PWB Part#	ABC_9230
FEA Min Elem Div	2	PWB Pre-Lamination Thickness	0.0624
FEA Aspect Ratio	4	PWB Post-Lamination Thickness	0.057599999999999999
Max Stress XX	3557.52	PWB Total Width	3.7999999999999999
Min Stress XX	-9867.29	PWB Total Length	3.9
Local Warpage	2.236E-4	Allowable Warpage Ratio	0.0075
Warpage Ratio	0.001940972222222224		
Margin of Safety	2.8640429338103752		
Create FEA Input	View FEA Input		

Calculate FEA Results

View Graphical Results

#### Case 3 Re-Design





## CONCLUSIONS

- WE ARE A SMALL BUSINESS WITH LIMITED ENGRG. RESOURCES
- U ENGINEER HAS PERMITTED US TO SOLVE SOME COMPLEX PROBLEMS
- WE NOW HAVE THE CAPABILITY TO PROVIDE A VALUABLE SERVICE TO THE CUSTOMER